

#### **General Description**

The MAX4686/MAX4687/MAX4688 low on-resistance (RON), low-voltage analog switches operate from a single +1.8V to +5.5V supply. The MAX4686/MAX4687 are single-pole/single-throw (SPST) analog switches, and the MAX4688 is a single-pole/double-throw (SPDT) analog switch. The MAX4686 is a normally open (NO) switch, and the MAX4687 is a normally closed (NC) switch. The MAX4688 has one normally open (NO) switch and one normally closed (NC) switch.

When powered from a 3V supply these devices feature  $2.5\Omega$  (max) R<sub>ON</sub>, with  $0.4\Omega$  (max) R<sub>ON</sub> matching and  $1\Omega$ (max) flatness. The MAX4686/MAX4687/MAX4688 offer fast switching speeds (ton = 30ns max, toff = 12ns max). The MAX4688 offers break-before-make action.

The digital logic inputs are 1.8V logic compatible from a +2.7V to +3.3V supply. The MAX4686/MAX4687/ MAX4688 are available in the chip-scale package (UCSP™), significantly reducing the required PC board area. The chip occupies only a 1.50mm x 1.02mm area. The 3 x 2 array of solder bumps are spaced with a 0.5mm bump pitch.

#### **Applications**

MP3 Players Cellular Phones Power Routing **Battery-Operated Equipment** Relay Replacement Audio and Video Signal Routing Communications Circuits **PCMCIA Cards** Cellular Phones Hard Drives

#### Features

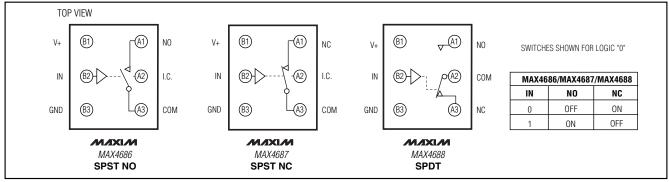
- ♦ 6-Bump, 0.5mm Pitch, UCSP (Package Pending **Full Qualification Expected Completion Date** 6/30/01. See UCSP Reliability Section for More Details.)
- ♦ Ron 2.5 $\Omega$  max (+3V Supply) 10 $\Omega$  max (+1.8V Supply)
- ♦ 0.4Ω max R<sub>ON</sub> Match Between Channels
- ♦ 1Ω max Ron Flatness Over Signal Range
- **♦ Low Leakage Currents Over Temperature** 0.5nA (max) at  $T_A = +25$ °C
- ♦ Fast Switching: toN = 30ns, toFF = 12ns
- ♦ Guaranteed Break-Before-Make (MAX4688)
- ♦ +1.8V to +5.5V Single-Supply Operation
- ♦ Rail-to-Rail<sup>®</sup> Signal Handling
- ♦ Low Crosstalk: -95dB (100kHz)
- ♦ High Off-Isolation: -90dB (100kHz)
- ♦ 1.8V Logic Compatible

### **Ordering Information**

PART	TEMP. RANGE	BUMP- PACKAGE	TOP MARK	
MAX4686EBT	-40°C to +85°C	6 UCSP*	AAI	
MAX4687EBT	-40°C to +85°C	6 UCSP*	AAJ	
MAX4688EBT	-40°C to +85°C	6 UCSP*	AAK	

<sup>\*</sup>UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and environment. Refer to the UCSP Reliability Notice in the UCSP Reliability section of this data sheet for more information.

### Pin Configurations/Functional Diagrams/Truth Table



Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd. UCSP is a trademark of Maxim Integrated Products, Inc.

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#### **ABSOLUTE MAXIMUM RATINGS**

All Voltages Referenced to GND	Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
V+, IN0.3V to +6V	3 x 2 UCSP (derate 10.1mW/°C at +70°C)808mW
COM, NO, NC (Note1)0.3V to (V+ + 0.3V)	Operating Temperature Range40°C to +85°C
Continuous Current NO, NC, COM±100mA	Storage Temperature Range65°C to +150°C
Peak Current NO, NC, COM	Bump Reflow Temperature+235°C
(pulsed at 1ms, 10% duty cycle)±200mA	

Note 1: Signals on NO, NC, and COM exceeding V+ are clamped by an internal diode. Limit forward-diode current to maximum current rating.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V+ = +2.7V \text{ to } +3.3V, V_{IH} = +1.4V, V_{IL} = 0.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at 3V and  $T_A = +25^{\circ}C.)$  (Notes 2, 8)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS	
ANALOG SWITCH			•	•				
Analog Signal Range	V <sub>COM</sub> , V <sub>NO</sub> , V <sub>NC</sub>		T <sub>MIN</sub> to T <sub>MAX</sub>	0		V+	V	
	R <sub>ON</sub>	V 0.7V V 0.1 V	+25°C		1.5	2.5		
On-Resistance		$V+ = 2.7V$ , $V_{NC} = 0$ to $V+$ , $I_{COM} = 10$ mA	T <sub>MIN</sub> to T <sub>MAX</sub>			3.5	Ω	
On-Resistance Match Between Channels	ARON	$V+ = 2.7V$ , $V_{NO}$ or $V_{NC} = 1.5V$ ,	+25°C		0.3	0.4	Ω	
(MAX4688 only) (Note 4)	ΔHON	$\Delta Ron$ $ICOM = 10mA$	T <sub>MIN</sub> to T <sub>MAX</sub>			0.5		
On Desistance Flatness		V. 07V V 07V 040V	+25°C	С	0.5	1	Ω	
On-Resistance Flatness (Note 5)	RFLAT(ON)	RFLAT(ON) $V+ = 2.7V, V_{NO} \text{ or } V_{NC} = 0 \text{ to } V+,$ $I_{COM} = 10\text{mA}$	T <sub>MIN</sub> to			1		
NO, NC Off-Leakage Current (Note 3)		I <sub>NO(OFF)</sub> , V+ = 3.3V; V <sub>COM</sub> = 0.3V or 3V; V <sub>NO</sub> or V <sub>NC</sub> = 3V, 0.3V	+25°C	-0.5	±0.01	+0.5	nA	
	- ( - /		$T_{MIN}$ to $T_{MAX}$	-1		1		
COM Off Leakage		$V_{NO} = 3.3V; V_{COM} = 0.3V \text{ or } 3V; V_{NO} = 0.3V \text{ or } 3V; V_{NO} = 3V, 0.3V$	+25°C	-0.5	±0.01	0.5	nA	
COM Off-Leakage Current (Note 3)	ICOM_(OFF)		$T_{MIN}$ to $T_{MAX}$	-1		1		
00110		V <sub>1</sub> = 2.2V: V <sub>2</sub> 2 v <sub>2</sub> = 2V or 0.2V:	+25°C	-0.5	±0.01	0.5		
COM On-Leakage Current (Note 3)	ICOM_(ON)	M_(ON) $V_{NO} = 3.3V; V_{COM} = 3V \text{ or } 0.3V; V_{NO} \text{ or } V_{NC} = 3V, 0.3V, \text{ or floating}$		-1		1	nA	
DYNAMIC CHARACTER	ISTICS							
Turn-On Time (Note 3)			+25°C		20	30	]	
	ton	V <sub>NO</sub> or V <sub>NC</sub> = 1.5V, Figure 2	$T_{MIN}$ to $T_{MAX}$	_		35	ns	
			+25°C		10	12		
Turn-Off Time (Note 3)	tOFF	V <sub>NO</sub> or V <sub>NC</sub> = 1.5V, Figure 2	T <sub>MIN</sub> to T <sub>MAX</sub>			15	ns	

#### **ELECTRICAL CHARACTERISTICS (continued)**

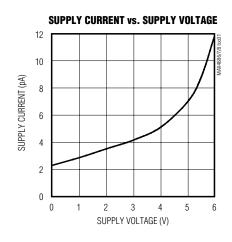
 $(V+=+2.7V \text{ to } +3.3V, V_{IH}=+1.4V, V_{IL}=0.5V, T_A=T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at 3V and  $T_A=+25^{\circ}C.)$  (Notes 2, 8)

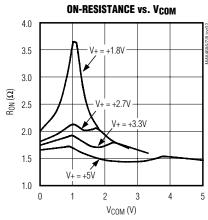
PARAMETER SYMBOL CONDITIONS		CONDITIONS	TA	MIN	TYP	MAX	UNITS	
			+25°C		8			
Break-Before-Make (MAX4688 only) (Note 3)	t <sub>BBM</sub>	V <sub>NO</sub> , V <sub>NC</sub> = 1.5V, Figure 3	T <sub>MIN</sub> to T <sub>MAX</sub>	2			ns	
Charge Injection	Q	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0, C <sub>L</sub> = 1.0nF, Figure 4 +25°C 40		40		рС		
On-Channel -3dB Bandwidth	BW	Signal = 0dBm, $50\Omega$ in and out, Figure 5	+25°C		200		MHz	
Off-Isolation (Note 6)	V <sub>ISO</sub>	$C_L = 5pF, R_L = 50\Omega, f = 100kHz,$ Figure 5 +25°C		-90		dB		
Crosstalk (MAX4688 only) (Note 7)	VCR	$C_L = 5pF$ , $R_L = 50\Omega$ , $f = 100kHz$ , Figure 5	+25°C		-95		dB	
Total Harmonic Distortion	THD	$R_L = 600\Omega$ , 2Vp-p, f = 20Hz to 20kHz	+25°C		0.06		%	
NO, NC Off- Capacitance	C <sub>NO(OFF)</sub> , C <sub>NC(OFF)</sub>	f = 1MHz, Figure 6	+25°C		12		pF	
COM Off-Capacitance	C <sub>COM</sub> (OFF)	f = 1MHz, Figure 6	+25°C		12		рF	
Switch On-Capacitance	C <sub>(ON)</sub>	f = 1MHz, Figure 6 +25°C 35		35		pF		
DIGITAL I/O								
Input Logic High	VIH		T <sub>MIN</sub> to T <sub>MAX</sub>	1.4			V	
Input Logic Low	VIL		T <sub>MIN</sub> to			0.5	V	
Logic Input Leakage Current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>IN</sub> = 0 or V+	T <sub>MIN</sub> to	-1		1	μА	
POWER SUPPLY								
Power-Supply Range	V+		T <sub>MIN</sub> to T <sub>MAX</sub>	1.8		5.5	V	
Supply Current	l+	V+ = 3.3V, V <sub>IN</sub> = 0 or V+	T <sub>MIN</sub> to T <sub>MAX</sub>	-1		1	μΑ	

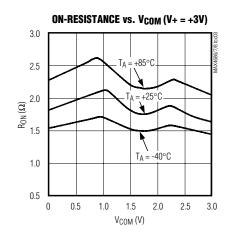
- **Note 2:** The algebraic convention, where the most negative value is a minimum and the most positive value a maximum, is used in this data sheet.
- Note 3: Guaranteed by design.
- **Note 4:**  $\Delta R_{ON} = R_{ON(MAX)} R_{ON(MIN)}$ , between switches.
- **Note 5:** Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.
- Note 6: Off Isolation = 20log<sub>10</sub> (V<sub>COM</sub> / V<sub>NO</sub>), V<sub>COM</sub> = output, V<sub>NO</sub> = input to off switch.
- Note 7: Between switches.
- Note 8: UCSP parts are 100% tested at +25°C only and guaranteed by correlation at the full hot-rated temperature.

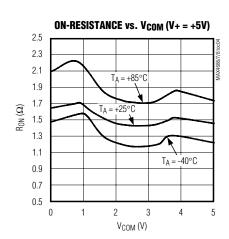
### **Typical Operating Characteristics**

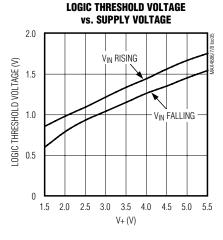
 $(T_A = +25$ °C, unless otherwise noted.)

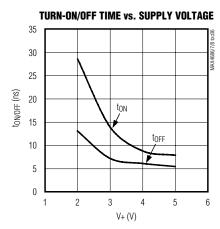


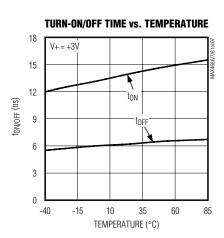


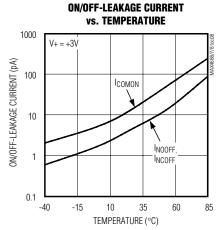


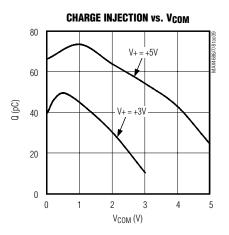






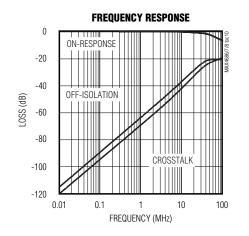


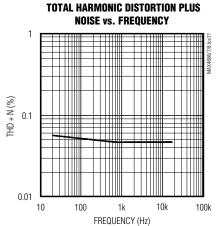




### Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 





#### \_Pin Description

	ВИМР		NAME	FUNCTION
MAX4686	MAX4687	MAX4688	INAME	FUNCTION
B1	B1	B1	V+	Positive Supply Voltage Input
B2	B2	B2	IN	Digital Control Input
В3	В3	B3	GND	Ground
_	A1	А3	NC	Analog Switch, Normally Closed Terminal
А3	A3	A2	COM	Analog Switch, Common Terminal
A1	_	A1	NO	Analog Switch, Normally Open Terminal
A2	A2	_	I.C.	Internally Connected

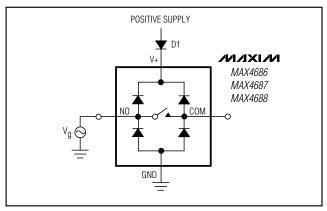


Figure 1. Overvoltage Protection Using External Blocking Diodes

### **Applications Information**

#### **Logic Inputs**

Where the MAX4686/MAX4687/MAX4688 have a +3.3V supply, IN may be driven low to GND and driven high to 5.5V. Driving IN rail-to-rail minimizes power consumption. Logic inputs accept up to +5.5V regardless of supply voltage.

#### **Analog Signal Levels**

Analog signals that range over the entire supply voltage (V+ to GND) are passed with very little change in R<sub>ON</sub> (see *Typical Operating Characteristics*). The switches are bidirectional, so the NO, NC, and COM pins are both inputs or outputs.

## Power-Supply Sequencing and Overvoltage Protection

CAUTION: Do not exceed the absolute maximum ratings because stresses beyond the listed ratings may cause permanent damage to devices.

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V+ before applying analog signals, especially if the analog signal is not current limited. If this sequencing is not possible, and if the analog inputs are not current limited to <20mA, add a small-signal diode (D1) as shown in Figure 1. Adding a protection diode reduces the analog range to a diode drop (about 0.7V) below V+ (for D1). Ron increases slightly at low supply voltages. Maximum supply voltage (V+) must not exceed +6V.Protection diode D1 also protects against some overvoltage situations. No damage will result on Figure 1's circuit if the supply voltage is below the absolute maximum rating and if a fault voltage up to the absolute maximum rating is applied to an analog signal pin.

#### **UCSP Package Consideration**

For general UCSP package information and PC layout considerations, please refer to the Maxim Application Note (Wafer-Level Ultra-Chip-Board-Scale Package).

#### **UCSP Reliability**

The chip-scale package (UCSP) represents a unique packaging form factor that may not perform equally to a packaged product through traditional mechanical reliability tests. CSP reliability is integrally linked to the user's assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering use of a CSP package. Performance through Operating Life Test and Moisture Resistance remains uncompromised as it is primarily determined by the wafer-fabrication process.

Mechanical stress performance is a greater consideration for a CSP package. CSPs are attached through direct solder contact to the user's PC board, foregoing the inherent stress relief of a packaged product lead frame. Solder joint contact integrity must be considered. Information on Maxim's qualification plan, test data, and recommendations are detailed in the UCSP application note, which can be found on Maxim's website at www.maxim-ic.com.

#### Test Circuits/Timing Diagrams

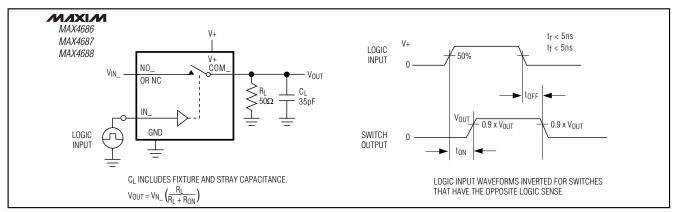


Figure 2. Switching Time

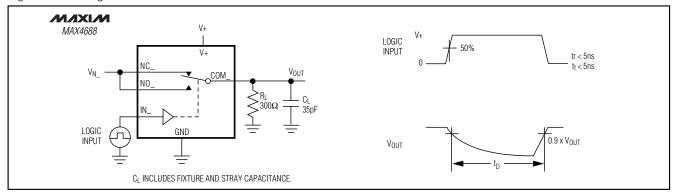


Figure 3. Break-Before-Make Interval (MAX4688 only)

#### **Test Circuits/Timing Diagrams (continued)**

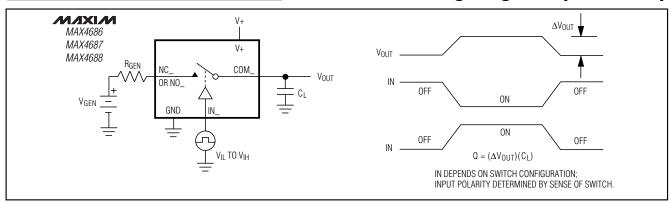


Figure 4. Charge Injection

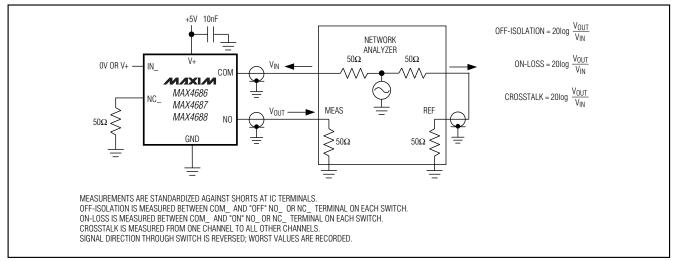


Figure 5. Off-Isolation/On-Channel Bandwidth, Crosstalk

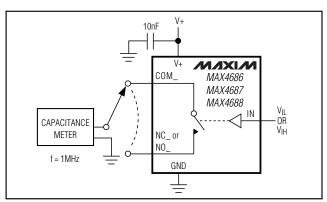
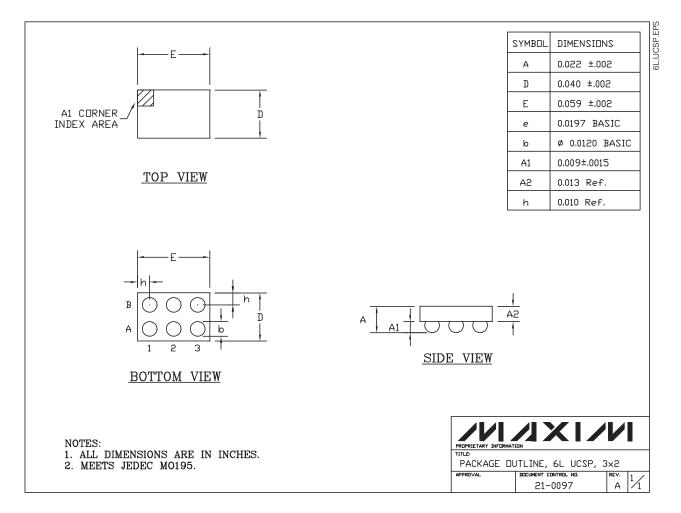


Figure 6. Channel Off/On-Capacitance

### \_Chip Information

**TRANSISTOR COUNT: 150** 

### Package Information



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